



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-08-04
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMG Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM6824MWY6F	DZWY*56VA9ML	A	ZS1A	2016-08-04
Amount	UoM	Unit type	ST ECOPACK Grade	
16.37	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOT	2.9 - 1.6 - 1.05	5	gull wing	
Comment	Package: SOT 23-5			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	DZWY*56VA9ML					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	0.562	mg	supplier	die	Silicon (Si)	7440-21-3		0.551	mg	980427	33659
Silicon die				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	3559	122
Silicon die				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	1779	61
Silicon die				supplier	Passivation	Silicon Nitride (SiN)	68034-42-4		0.002	mg	3559	122
Silicon die				supplier	Passivation	Silicon Oxide (SiO2)	7631-86-9		0.006	mg	10676	367
Leadframe	Copper & its alloys	6.791	mg	supplier	alloy	Copper (Cu)	7440-50-8		6.524	mg	960683	398534
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.164	mg	24150	10018
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.002	mg	295	122
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.009	mg	1325	550
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.084	mg	12369	5131
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.007	mg	1031	428
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	147	61
Die attach	Other inorganic materials	0.078	mg	supplier	glue	Silver (Ag)	7440-22-4		0.056	mg	717949	3421
Die attach				supplier	glue	methylene diacrylate	42594-17-2		0.013	mg	166667	794
Die attach				supplier	glue	Dicyclopentenyloxyethyl methacrylate	68586-19-6		0.003	mg	38462	183
Die attach				supplier	glue	Bismaleimide resin	35325-39-4		0.003	mg	38462	183
Die attach				supplier	glue	Palladium (Pd)	7440-05-3		0.001	mg	12821	61
Die attach				supplier	glue	Dicumyl peroxide	80-43-3		0.002	mg	25641	122
Bonding wire	Precious metals	0.154	mg	supplier	wire	Gold (Au)	7440-57-5		0.154	mg	1000000	9407
encapsulation	Other inorganic materials	8.785	mg	supplier	mold compound	Epoxy Resin	25068-38-6		0.348	mg	39613	21258
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.131	mg	14912	8002
encapsulation				supplier	mold compound	Phenol resin	29690-82-2		0.363	mg	41320	22175
encapsulation				supplier	mold compound	Silica	60676-86-0		7.04	mg	801366	430055
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		0.016	mg	1821	977
encapsulation				supplier	mold compound	Zinc hydroxide	20427-58-1		0.162	mg	18441	9896
encapsulation				supplier	mold compound	Magnesium hydroxide	1309-42-8		0.725	mg	82527	44288